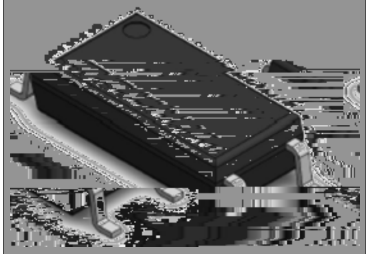
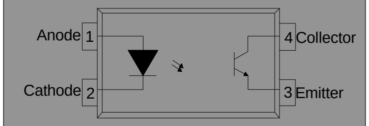
The products are transistor opto-couplers in a plastic LSOP4 package. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector. With the robust coplanar double mold structure, the device provides the most stable isolation feature. The products are widely used in switch mode power supplies, programmable controllers, household appliances, office equipment, etc.





High isolation 5000 VRMS
DC input with transistor output
Operating temperature range -40°C to 110°C
RoHS & REACH Compliance
HBM: H3A ; MM: M4; CDM:C3
CQC approved
VDE approved
UL approved

(Temperature=25°C)

Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation	P_D	75	mW
Output	Collector-emitter Voltage	V_{CEO}	80	V
	Emitter-collector Voltage	V_{ECO}	7	V
	Collector Current	I_C	50	mA
	Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	225	mW
Isolation Voltage		V_{iso}	5000	Vrms
Operating Temperature		T_{opr}	-40~+110	
Junction Temperature		T_j	125	

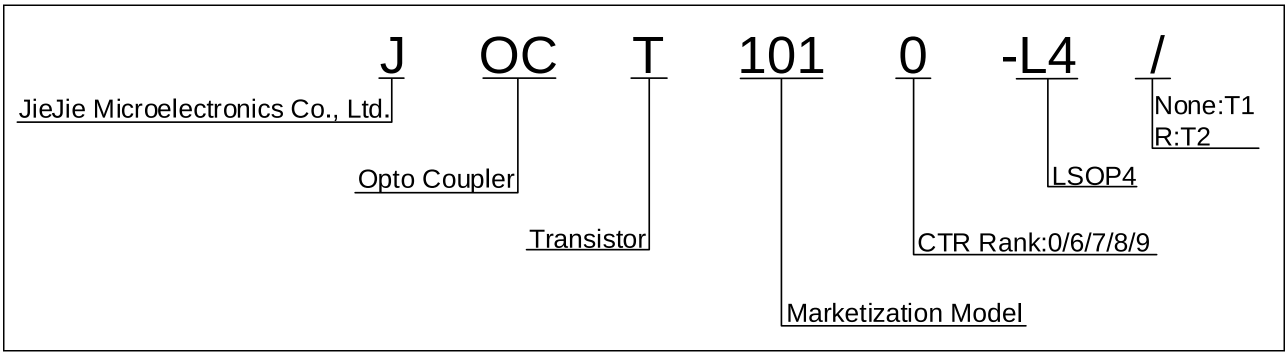
Storage Temperature	T_{stg}	-55~+125	
Soldering Temperature	T_{sol}	260	

:100μs pulse, 100Hz frequency

:AC for 1minute, R.H.=40~60%

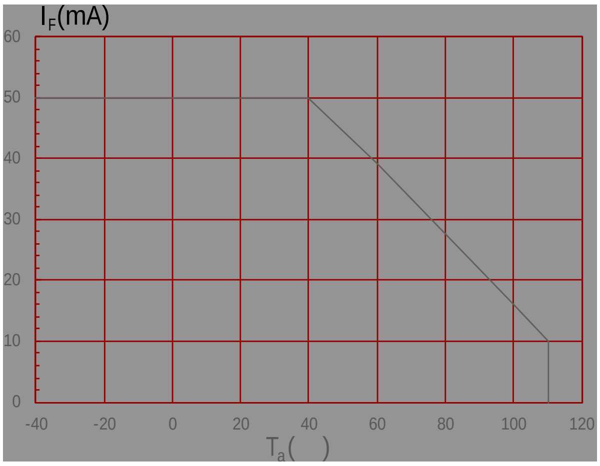
(Temperature=25°C)

Input	Forward Voltage	V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA

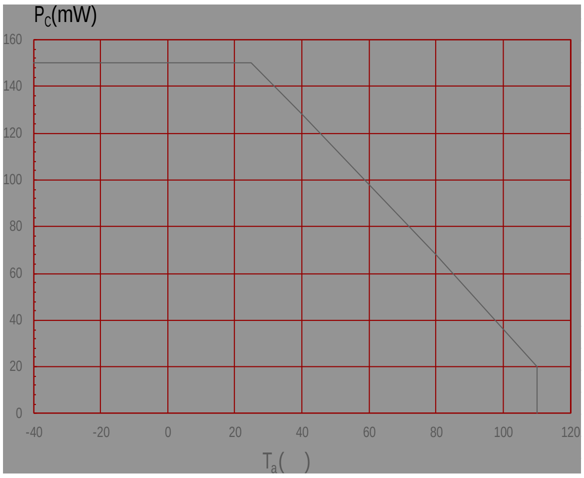


None/R	3000 Units/Reel

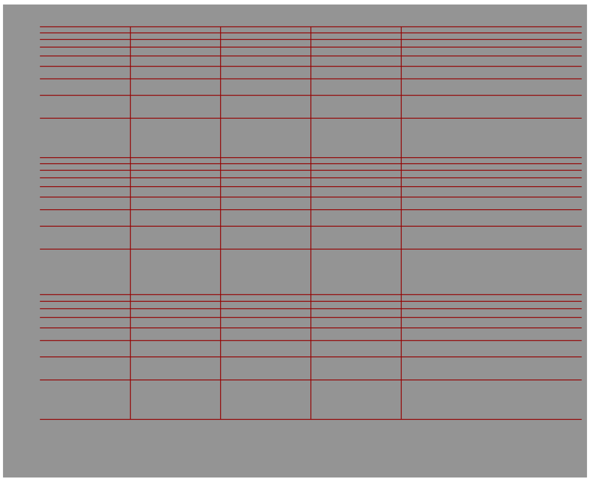
Max. Allowable LED Forward Current vs. Ambient Temperature



Collector Power Dissiption vs. Ambient Temperature

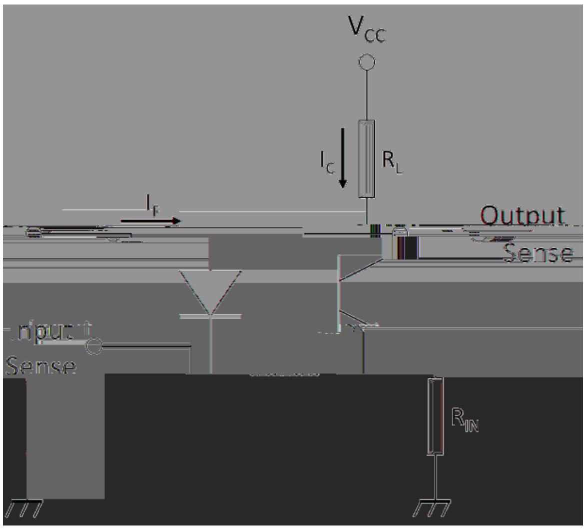


Forward Current vs. Forward Voltage

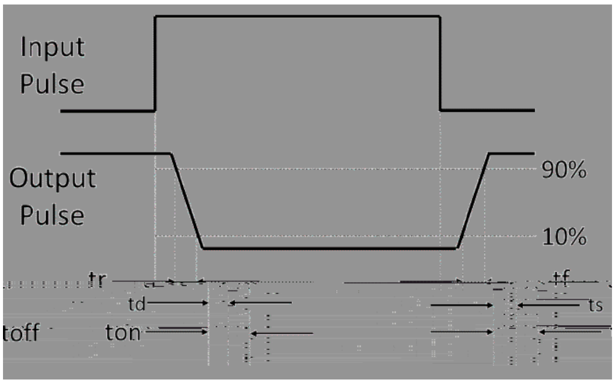


Normalized Collector Dark Current vs. Ambient Temperature

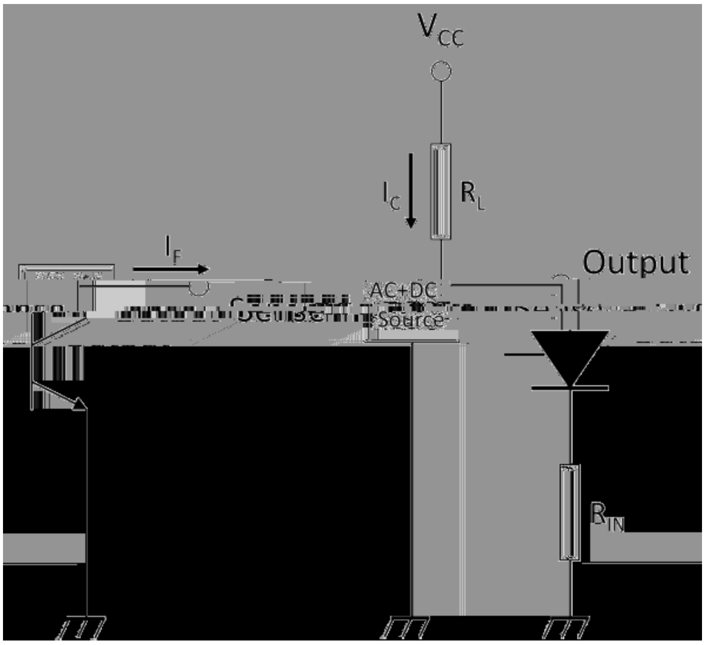
Test Circuits of Response Time

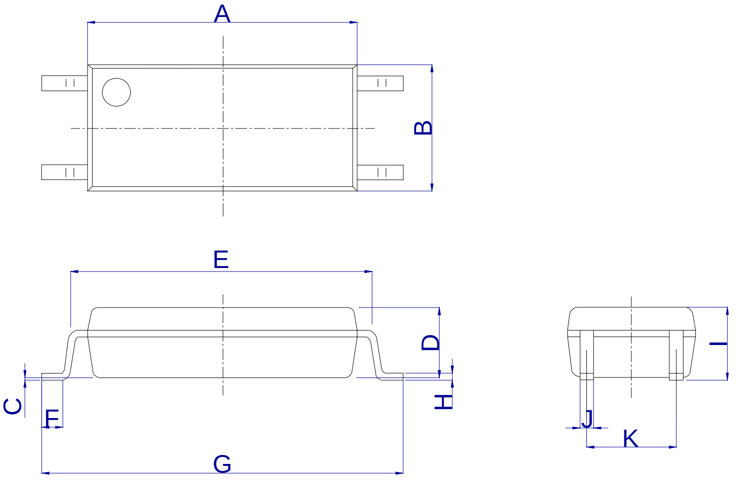


Curves of Response Time

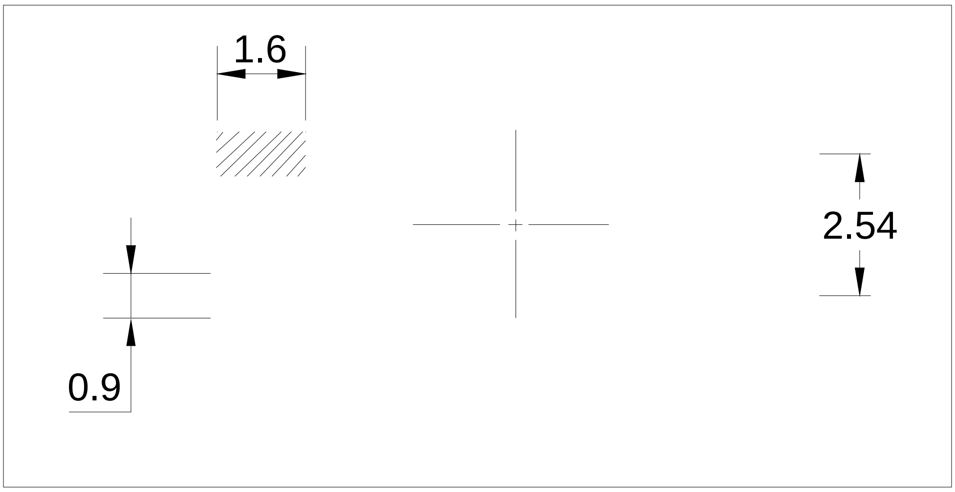


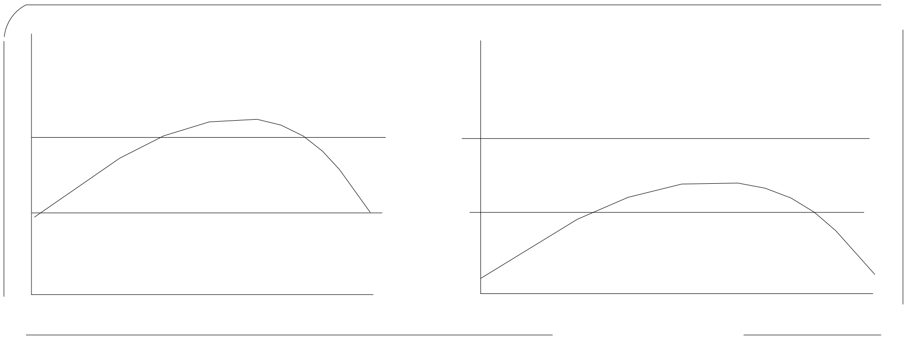
Test Circuits of Frequency Response

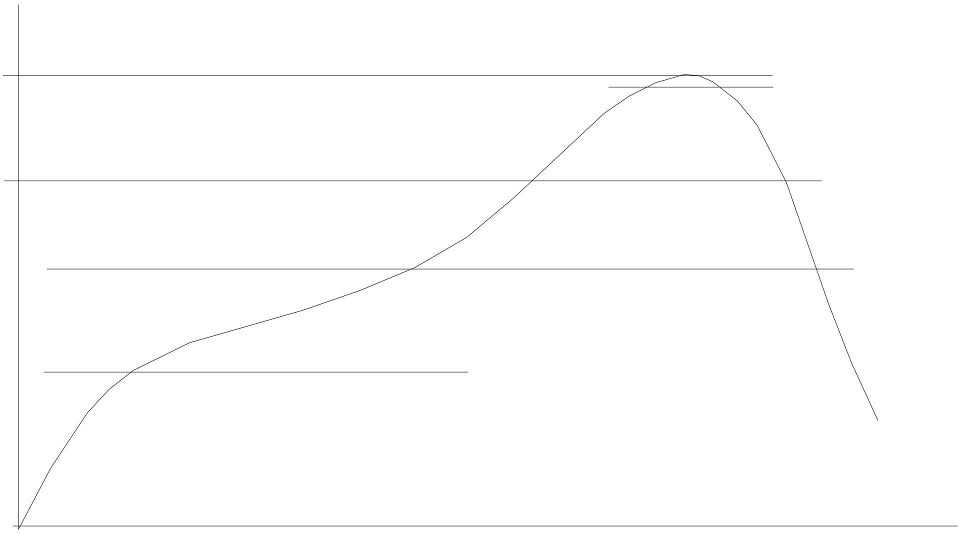




Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.40		1.00	0.016		0.039
G	9.90		10.50	0.390		0.413
H	0.10		0.30	0.004		0.012
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K	2.29		2.79	0.090		0.110







Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum